# 6-Pin DIP Random-Phase **Triac Driver Output Optocoupler** (250/400 V Peak)

### Description

The MOC301XM and MOC302XM series are optically isolated triac driver devices. These devices contain a GaAs infrared emitting diode and a light activated silicon bilateral switch, which functions like a triac. They are designed for interfacing between electronic controls and power triacs to control resistive and inductive loads for 115 V<sub>AC</sub> operations.

### **Features**

- Excellent I<sub>FT</sub> Stability IR Emitting Diode Has Low Degradation
- Peak Blocking Voltage
  - 250 V, MOC301XM
  - ◆ 400 V, MOC302XM
- Safety and Regulatory Approvals
  - UL1577, 4,170 VAC<sub>RMS</sub> for 1 Minute
  - ◆ DIN EN/IEC60747-5-5
- These are Pb-Free Devices

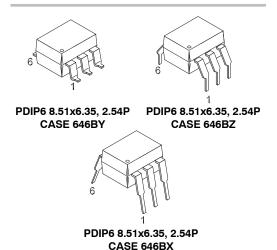
## **Applications**

- Industrial Controls
- Solenoid/Valve Controls
- Traffic Lights
- Static AC Power Switch
- Vending Machines
- Incandescent Lamp Dimmers
- Solid State Relay
- Motor Control
- Lamp Ballasts



### ON Semiconductor®

www.onsemi.com



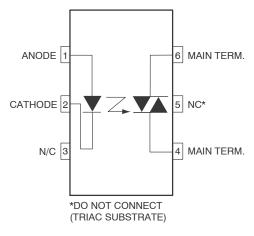


Figure 1. Schematic

### ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

1

# **SAFETY AND INSULATION RATINGS**

As per DIN EN/IEC 60747–5–5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter	Characteristics	
Installation Classifications per DIN VDE 0110/1.89 Table 1, For	< 150 V <sub>RMS</sub>	I–IV
Rated Mains Voltage	< 300 V <sub>RMS</sub>	I–IV
Climatic Classification	40/85/21	
Pollution Degree (DIN VDE 0110/1.89)	2	
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
$V_{PR}$	Input–to–Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$ , Type and Sample Test with $t_m$ = 10 s, Partial Discharge < 5 pC	1275	Vpeak
	Input–to–Output Test Voltage, Method B, $V_{\rm IORM}$ x 1.875 = $V_{\rm PR}$ , 100% Production Test with $t_{\rm m}$ = 1 s, Partial Discharge < 5 pC	1594	Vpeak
V <sub>IORM</sub>	Maximum Working Insulation Voltage	850	Vpeak
$V_{IOTM}$	Highest Allowable Over-Voltage	6000	Vpeak
	External Creepage	≥7	mm
	External Clearance	≥7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V	> 10 <sup>9</sup>	Ω

# **ABSOLUTE MAXIMUM RATINGS** (T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameters	Device	Value	Unit
otal Device				
T <sub>STG</sub>	Storage Temperature	All	-40 to 150	°C
T <sub>OPR</sub>	Operating Temperature	All	-40 to 85	°C
TJ	Junction Temperature Range	All	-40 to 100	°C
T <sub>SOL</sub>	Lead Solder Temperature	All	260 for 10 seconds	°C
Б	Total Device Power Dissipation at 25°C Ambient	All	330	mW
$P_D$	Derate Above 25°C		4.4	mW/°C
mitter				
I <sub>F</sub>	Continuous Forward Current	All	60	mA
$V_{R}$	Reverse Voltage	All	3	V
В	Total Power Dissipation at 25°C Ambient	All	100	mW
$P_D$	Derate Above 25°C	All	1.33	mW/°C
etector				
$V_{DRM}$	Off-State Output Terminal Voltage	MOC3010M, MOC3011M, MOC3012M	250	٧
		MOC3020M, MOC3021M, MOC3022M, MOC3023M	400	
I <sub>TSM</sub>	Peak Repetitive Surge Current (PW = 100 μs, 120 pps)	All	1	Α
В	Total Power Dissipation at 25°C Ambient	All	300	mW
$P_D$	Derate Above 25°C	All	4	mW/°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## **ELECTRICAL CHARACTERISTICS**

 $T_A = 25$ °C unless otherwise specified

### INDIVIDUAL COMPONENT CHARACTERISTICS

Symbol	Parameters	Test Conditions	Device	Min.	Тур.	Max.	Unit
Emitter							
V <sub>F</sub>	Input Forward Voltage	I <sub>F</sub> = 10 mA	All		1.15	1.50	V
I <sub>R</sub>	Reverse Leakage Current	V <sub>R</sub> = 3 V, T <sub>A</sub> = 25°C	All		0.01	100	μΑ
Detector							
I <sub>DRM</sub>	Peak Blocking Current, Either Direction	Rated $V_{DRM}$ , $I_F = 0^{(1)}$	All		10	100	nA
$V_{TM}$	Peak On-State Voltage, Either Direction	$I_{TM} = 100 \text{ mA peak}, I_F = 0$	All		1.8	3.0	٧

<sup>1.</sup> Test voltage must be applied within dv/dt rating.

### TRANSFER CHARACTERISTICS

Symbol	DC Characteristics	Test Conditions	Device	Min.	Тур.	Max.	Unit
I <sub>FT</sub>	LED Trigger Current	Voltage = 3 V <sup>(2)</sup>	MOC3020M			30	mA
			MOC3010M			15	
			MOC3021M			15	
			MOC3011M		10	10	
			MOC3022M				
			MOC3012M			5	
			MOC3023M			3	
I <sub>H</sub>	Holding Current, Either Direction		All		100		μΑ

<sup>2.</sup> All devices are guaranteed to trigger at an I<sub>F</sub> value less than or equal to max I<sub>FT</sub>. Therefore, recommended operating I<sub>F</sub> lies between max I<sub>FT</sub> (30 mA for MOC3020M, 15 mA for MOC3010M and MOC3021M, 10 mA for MOC3011M and MOC3022M, 5 mA for MOC3012M and MOC3023M) and absolute maximum I<sub>F</sub> (60 mA).

### **ISOLATION CHARACTERISTICS**

Symbol	Parameters	Test Conditions	Device	Min.	Тур.	Max.	Unit
V <sub>ISO</sub>	Isolation Voltage (3)	t = 1 Minute	All	4170			VAC <sub>RMS</sub>

<sup>3.</sup> Isolation voltage, V<sub>ISO</sub>, is an internal device dielectric breakdown rating. For this test, pins 1 and 2 are common, and pins 4, 5 and 6 are common.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **TYPICAL PERFORMANCE CURVES**

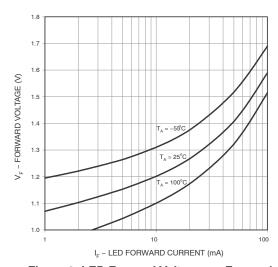


Figure 2. LED Forward Voltage vs. Forward Current

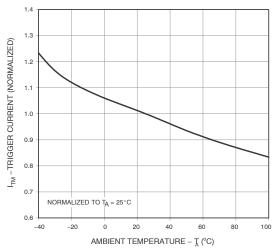


Figure 4. Trigger Current vs. Ambient Temperature

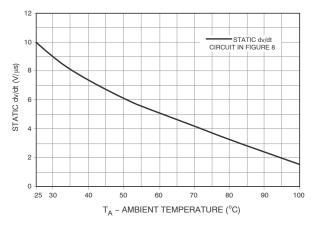


Figure 6. dv/dt vs. Temperature

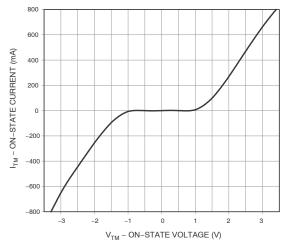


Figure 3. On-State Characteristics

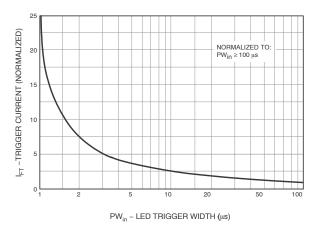


Figure 5. LED Current Required to Trigger vs. LED Pulse Width

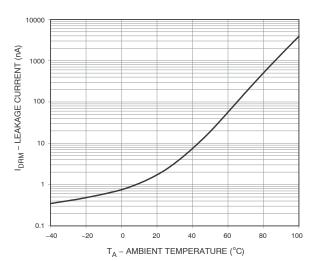
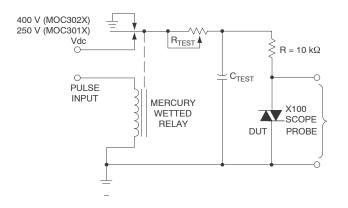
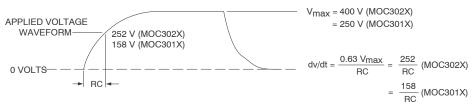


Figure 7. Leakage Current, I<sub>DRM</sub> vs. Temperature



- 1. The mercury wetted relay provides a high speed repeated pulse to the D.U.T.
- 2. 100x scope probes are used, to allow high speeds and voltages.
- 3. The worst–case condition for static dv/dt is established by triggering the DUT with a normal LED input current, then removing the current. The variable R<sub>TEST</sub> allows the dv/dt to be gradually increased until the DUT continues to trigger in response to the applied voltage pulse, even after the LED current has been removed. The dv/dt is then decreased until the DUT stops triggering. τ <sub>BC</sub> is measured at this point and recorded.



#### Note:

This optoisolator should not be used to drive a load directly. It is intended to be a trigger device only.

Figure 8. Static dv/dt Test Circuit

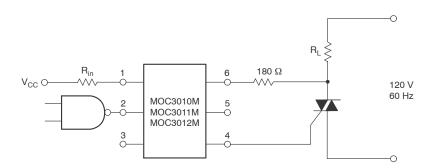


Figure 9. Resistive Load

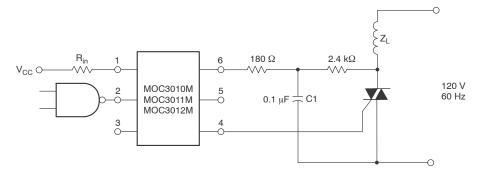


Figure 10. Inductive Load with Sensitive Gate Triac (I<sub>GT</sub> ≤ 15 mA)

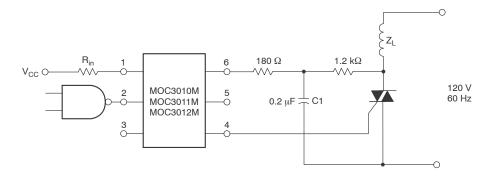
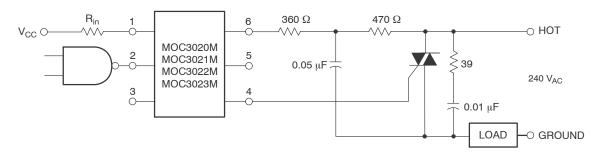


Figure 11. Inductive Load with Sensitive Gate Triac (I<sub>GT</sub> ≤ 15 mA)



In this circuit the "hot" side of the line is switched and the load connected to the cold or ground side. The 39  $\Omega$  resistor and 0.01  $\mu$ F capacitor are for snubbing of the triac, and the 470  $\Omega$  resistor and 0.05  $\mu$ F capacitor are for snubbing the coupler. These components may or may not be necessary depending upon the particular and load used.

Figure 12. Typical Application Circuit

### **Reflow Profile**

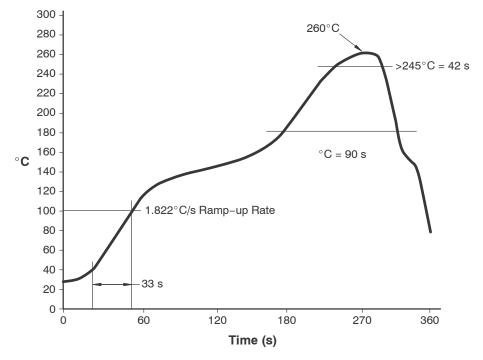


Figure 13. Reflow Profile

## **ORDERING INFORMATION**

Part Number	Package	Shipping	
MOC3010M	DIP 6-Pin	50 Units / Tube	
MOC3010SM	SMT 6-Pin (Lead Bend)	50 Units / Tube	
MOC3010SR2M	SMT 6-Pin (Lead Bend)	1000 Units / Tape & Reel	
MOC3010VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	50 Units / Tube	
MOC3010SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	50 Units / Tube	
MOC3010SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	1000 Units / Tape & Reel	
MOC3010TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	50 Units / Tube	

NOTE: The product orderable part number system listed in this table also applies to the MOC3011M, MOC3012M, MOC3020M, MOC3021M, MOC3022M, and MOC3023M product families.

### **MARKING INFORMATION**

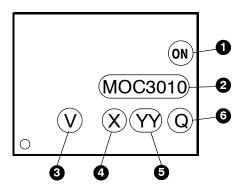
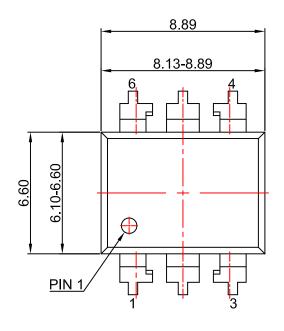


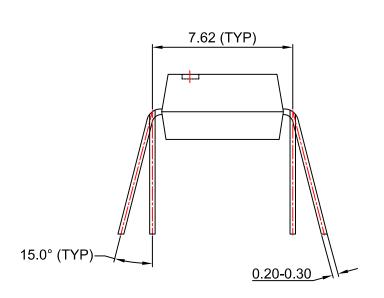
Figure 14. Top Marking

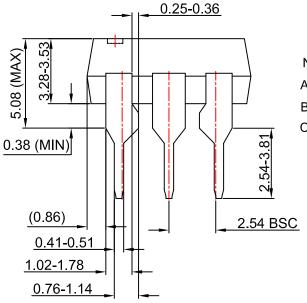
	Top Mark Definitions				
1	ON Semiconductor Logo				
2	Device Number				
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)				
4	One-Digit Year Code, e.g., '5'				
5	Two-Digit Work Week, Ranging from '01' to '53'				
6	Assembly Package Code				

### PDIP6 8.51x6.35, 2.54P CASE 646BX ISSUE O

**DATE 31 JUL 2016** 







### NOTES:

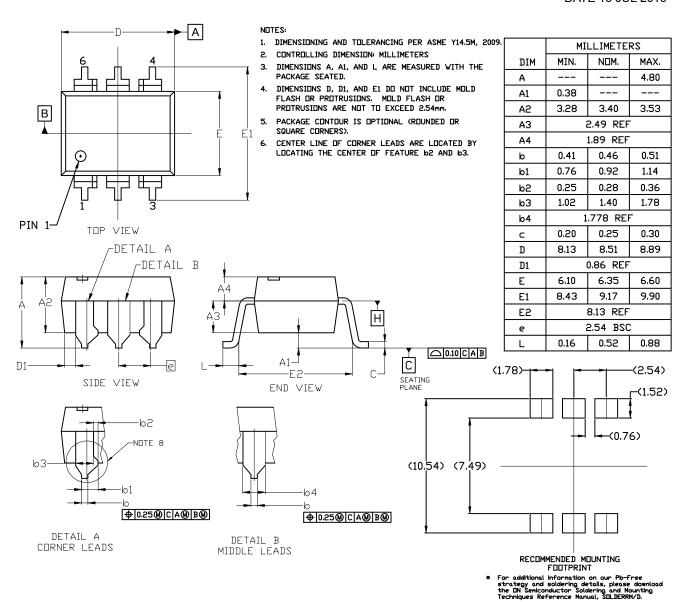
- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

DOCUMENT NUMBER:	98AON13449G	Electronic versions are uncontrolled except when accessed directly from the Document Reposito Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	PDIP6 8.51X6.35, 2.54P		PAGE 1 OF 1	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

### PDIP6 8.51x6.35, 2.54P CASE 646BY ISSUE A

**DATE 15 JUL 2019** 

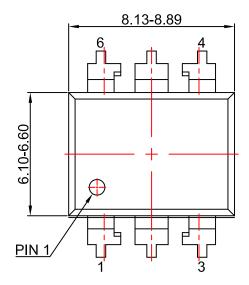


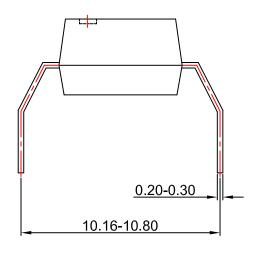
DOCUMENT NUMBER:	98AON13450G	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED (	
DESCRIPTION:	PDIP6 8.51x6.35, 2.54P		PAGE 1 OF 1

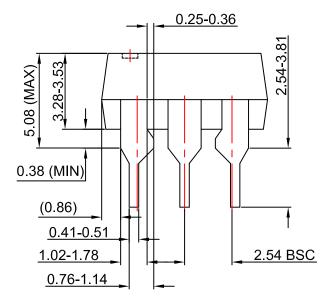
ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

### PDIP6 8.51x6.35, 2.54P CASE 646BZ ISSUE O

**DATE 31 JUL 2016** 







### NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

DOCUMENT NUMBER:	98AON13451G	Electronic versions are uncontrolled except when accessed directly from the Document Repos Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	PDIP6 8.51X6.35, 2.54P		PAGE 1 OF 1	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative